

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Tongbi Jiang

Application No.: 09/484,437

Confirmation No.: 9698

Filed: January 18, 2000

Art Unit: 2813

For: Die attach curing method for semiconductor
device

Examiner: J. M. Mitchell

AMENDMENT AFTER FILING OF REQUEST FOR CONTINUED EXAMINATION

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

Further to Applicant's filing of a Request for Continued Examination along with the necessary fees, please consider the following Amendments.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.